

IN THE CLAIMS

1. (Currently Amended) An energization processing apparatus for performing, in a reduced-pressure atmosphere, an energization process on electric conductors which are placed on a substrate, comprising:

a vessel which has an exhaust hole and which covers the electric conductors and one region on a surface of the substrate where the electric conductors are placed, to create an airtight atmosphere between the substrate and the vessel, wherein the vessel does not cover a further region on the surface of the substrate is located outside of the vessel, and wherein the one region is under reduced-pressure atmosphere and the further region is under atmospheric air.[:]

a first temperature adjusting mechanism for generating a heat quantity per unit area to adjust a temperature of the one region; and

a second temperature adjusting mechanism for generating a heat quantity per unit area, which is different from the heat quantity per unit area generated by the second temperature adjusting mechanism, to adjust a temperature of the further region[.,].

wherein the heat quantity generated by the first temperature adjusting mechanism is different from the heat quantity generated by the second temperature adjusting mechanism:

2. (Canceled)

3. (Currently Amended) An energization processing method for performing, in a reduced-pressure atmosphere, an energization process on electric conductors which are placed on a substrate, comprising the steps of:

covering the electric conductors and one region on a surface of the substrate where the electric conductors are placed with a vessel which has an exhaust hole, to create an airtight atmosphere between the substrate and the vessel, wherein the vessel does not cover a further region on the surface of the substrate is located outside of the vessel;

reducing a pressure of the airtight atmosphere, wherein the one region is under reduced-pressure atmosphere and the further region is under atmospheric air; and

heating the one region with a smaller heat quantity per unit area while heating the further region with a larger heat quantity per unit area so as to suppress a temperature difference between the one region and the further region.

4. (Canceled)

5. (Previously Presented) The energization processing apparatus according to claim 1, wherein

the first temperature adjusting mechanism has a first thermal conducting member touching a surface of the substrate just opposite to the one region,

while the second temperature adjusting mechanism has a second thermal conducting member touching a surface of the substrate just opposite to the further region.

6. (Previously Presented) The energization processing apparatus according to claim 1, wherein

the second temperature adjusting mechanism is capable of thermal generation larger than that of the first temperature adjusting mechanism, to suppress a temperature difference between the one region and the further region.

7. (New) The energization processing apparatus according to claim 1, further comprising,

a heat insulating member located at a side opposing the further region on the surface of the substrate.